

INTEGRATION REPORT

Report No.:SHR06102630392001-1

Date :Nov. 3, 2006

Page 1 of 3

Client Hengfu Corporation

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Integrated Samples Description:

Sample Name Switching Power Supply

产品名称 开关电源

Test Model Switching Power Supply - Complete Range

产品型号 全系列开关电源

Additional Model

附属型号 /

Buyer

买家 /

Sample Received Date

产品接收日期

Oct. 26, 2006

Completed Date

完成日期

Nov. 3, 2006

Test Specification

测试规范

:According to EC Directive 2002/95/EC (RoHS) and clients request, to determine The Hazardous Substances in Electrical and Electronic Equipment.

依据 EC Directive 2002/95/EC (RoHS)指令及客户要求, 测定电子电气设备中的有害物质。

Requirement

要求

:To combine the components test reports according to the clients request, the clients should be responsible for the authenticity and validity of the reports.

依据客户要求整合零部件测试报告, 客户应对递交报告的真实性、有效性负责。

Conclusion

结论

:PASS (通过)

With reference to IEC 62321, Ed.1, the submitted complete product is tested by "homogeneous material" principle. The test result stated as is compliant with the requirement of the EC Regulations (RoHS).After assessing all the datas in the test report, we hereby certify the test method is proved to conform to RoHS standard, and the test result is well under the RoHS limit,so the complete range of Switching Power Supplies manufactured by Hengfu, which are made from the substances listed below, are RoHS compliant.

依据 IEC 62321, Ed.1 原则, 提交的整套产品是根据“同质材料”原则进行测试的, 测试结果符合 EC 规定 (RoHS) 要求。经对测试报告中的所有数据进行审核, 我们特此证明该测试方法经证实符合 **RoHS** 测试标准, 测试结果低于 RoHS 规定的限值。由此证明衡孚公司采用下列清单所包含的材料生产的全系列开关电源产品符合 **RoHS** 标准。

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Report No.:SHR06102630392001-1

Date :Nov. 3, 2006

Page 2 of 3

CONTENTS

Complete Product Photo	3
Attached Pages I	
Exempt Items	
Attached Pages II	
Bill of Materials (BOM) & Test results	

Written by Star Zhao

Tested by Judy Xiong
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Inspected by _____

Approved by Jesie Chen

Position Manager

Date Nov. 3, 2006

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CTI Physical & Chemical Lab.

*** End of Report ***



Photo: Sample

SHR06102630392001-1



Exempt Items

The below exempt items published in EU commission official journal

1. Mercury in compact fluorescent lamps not exceeding 5mg per lamp.
2. Mercury in straight fluorescent lamps for general purposes not exceeding:
 - Halophosphate 10mg
 - Triphosphate with normal lifetime 5 mg
 - Triphosphate with long lifetime 8 mg
3. Mercury in straight fluorescent lamps for special purpose.
4. Mercury in other lamps not specifically mentioned in this Annex.
5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
6. Lead as an alloying element in steel containing up to 0.35% lead by weight, aluminium containing up to 0.4% lead by weight and as a copper alloy containing up to 4% lead by weight.
7. – Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
 - Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
 - Lead in electronic ceramic parts(e.g. piezoelectronic devices).
8. Cadmium and its compounds in electrical contacts and cadmium plating except for application banned under directive 91/338/EEC amending directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations.
9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.
- 9a. DecaBDE in polymeric applications.
- 9b. Lead in lead-bronze bearing shells and bushes.
10. Within the procedure referred to in Article 7(2), the commission shall evaluate the applications for:
 - Deca BDE
 - Mercury in straight fluorescent lamps for special purposes,
 - Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications(with a view to setting a specific time limit for this exemption),and
 - Light bulbs,As a matter of priority in order to establish as soon as possible whether these items are to be amended accordingly.
11. Lead used in compliant pin connector systems.
12. Lead as a coating material for the thermal conduction module c-ring.
13. Lead and cadmium in optical and filter glass.
14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% by weight.
15. Lead in solders to complete a viable electrical between semiconductor die and carrier within integrated circuit Flip Chip packages.



Attached page II

Exempt Items

The below exempt items published in EU commission official journal

16. Lead in linear incandescent lamps with silicate coated tubes.
17. Lead halide as radiant agent in High Intensity Discharge (HID) lamps used for – professional reprography applications.
18. Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge –lamps when used as sun tanning lamps containing phosphors such as BSP ($\text{BaSi}_2\text{O}_5:\text{Pb}$) as –well as when used as speciality lamps for diazo-printing reprography, lithography, –insect traps, photochemical and curing processes containing phosphors such as SMS –($(\text{Sr},\text{Ba})_2\text{MgSi}_2\text{O}_7:\text{Pb}$) .
19. Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with – PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL) .
20. Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCD) .
21. Lead and cadmium in printing inks for the application of enamels on borosilicate glass.
22. Lead as impurity in RIG(rare earth iron gamet)Faraday rotators used for fiber optic communications systems.
23. Lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with NiFe lead frames and lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with copper lead frames.
24. Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors.
25. Lead oxide in plasma display panels (PDP) and surface conduction electron emitter displays(SED) used in structural elements; notably in the front and rear glass dielectric layer, the bus electrode, the black stripe, the address electrode, the barrier ribs, the seal frit and frit ring as well as in print pastes.
26. Lead oxide in glass envelope of Black Light Blue (BLB) lamps.
27. Lead alloys as solder for transducers used in high-powered (designated to operate for several hours at acoustic power levels of 125 Db SPL and above) loudspeaker.
28. Lead bound in crystal glass as defined in Annex I(Categories 1,2,3 and 4)of Council Directive 69/493/EEC(*)
29. Hexavalent chromium in corrosion preventive coatings of unpainted metal sheetings and fasteners used for corrosion protection and Electromagnetic interference shielding in equipment falling under category three of directive 2002/96/EC(IT and telecommunications equipment).Exemption granted until 1 July 2007.

